

S-8261 Series

Rev.5.0 00

BATTERY PROTECTION IC FOR 1-CELL PACK

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The S-8261 series are lithium-ion / lithium polymer rechargeable battery protection ICs incorporating high-accuracy voltage detection circuit and delay circuit.

The S-8261 series are suitable for protection of single-cell lithium ion/lithium polymer battery packs from overcharge, overdischarge and overcurrent.

Features

- (1) Internal high accuracy voltage detection circuit Overcharge detection voltage 3.9 V to 4.4 V (applicable in 5 mV step) Accuracy: ±25 mV (+25°C) and ±30 mV (-5°C to +55°C)
 - 0.1 V to 0.4 V^{*1} Overcharge hysteresis voltage Accuracy: ±25 mV The overcharge hysteresis voltage can be selected from the range 0.1 V to 0.4 V in 50 mV step.
 - Overdischarge detection voltage 2.0 V to 3.0 V (applicable in 10 mV step) Accuracy: ±50 mV 0.0 V to 0.7 V*2 Overdischarge hysteresis voltage Accuracy: ±50 mV
 - The overdischarge hysteresis voltage can be selected from the range 0.0 V to 0.7 V in 100 mV step.
 - Overcurrent 1 detection voltage 0.05 V to 0.3 V (applicable in 10 mV step) Accuracy: ±15 mV
 - Overcurrent 2 detection voltage 0.5 V (fixed) Accuracy: ±100 mV
- High voltage device is used for charger connection pins (VM and CO pins: absolute maximum rating = 28 V). (2)
- Delay times (overcharge: t_{CU}, overdischarge: t_{DL}, overcurrent 1: t_{IOV1}, overcurrent 2: t_{IOV2}) are generated by an (3) internal circuit. No external capacitor is necessary. Accuracy: ±20%
- (4) Three-step overcurrent detection circuit is included (overcurrent 1, overcurrent 2 and load short-circuiting).
- (5) 0 V battery charge function "Available" / "Unavailable" are selectable.
- Power-down function "Yes" / "No" are selectable. (6)
- (7) Charger detection function and abnormal charge current detection function
 - The overdischarge hysteresis is released by detecting negative voltage at the VM pin (-0.7 V typ.) (Charger detection function).
 - When the output voltage of the DO pin is high and the voltage at the VM pin is equal to or lower than the charger detection voltage (-0.7 V typ.), the output voltage of the CO pin goes low (Abnormal charge current detection WWW.DZSC.COM function).
- (8) Low current consumption
 - Operation mode 3.5 μA typ., 7.0 μA max.
 - Power-down mode 0.1 µA max.
- Wide operating temperature range -40°C to +85°C (9)
- (10) Lead-free, Sn 100%, halogen-free*3
- *1. Overcharge release voltage = Overcharge detection voltage Overcharge hysteresis voltage (where overcharge release voltage < 3.8 V is prohibited.)
- *2. Overdischarge release voltage = Overdischarge detection voltage + Overdischarge hysteresis voltage (where overdischarge release voltage > 3.4 V is prohibited.)
- Refer to "
 Product Name Structure" for details.

Applications

- Lithium-ion rechargeable battery packs
- Lithium polymer rechargeable battery packs
- Package
 - SOT-23-6



LOW DROPOUT CMOS VOLTAGE REGULATOR S-8261 Series

Rev.5.0_00

Block Diagram

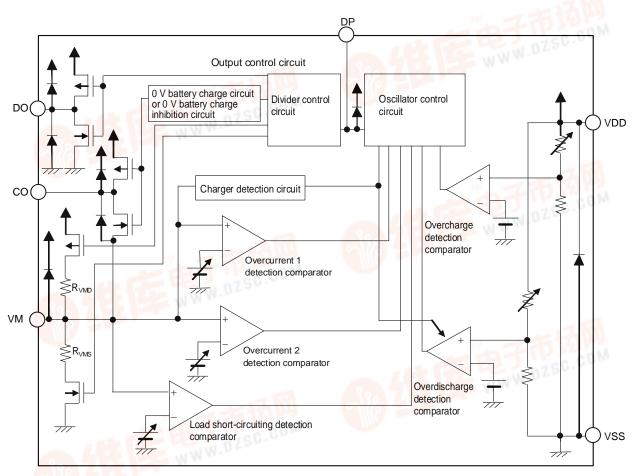
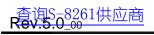


Figure 1

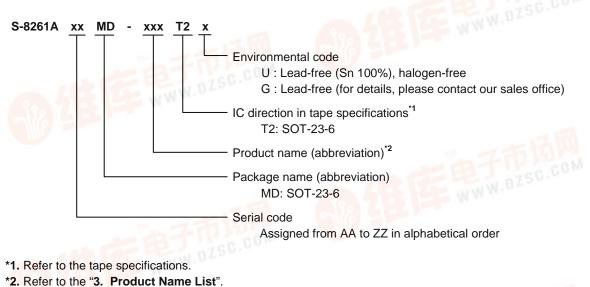
Remark All the diodes shown in the figure are parasitic diodes.





Product Name Structure

1. Product Name



2. Package

Bookago nomo	A THORE COM	Drawing code	
Package name	Package	Таре	Reel
SOT-23-6	MP006-A-P-SD	MP006-A-C-SD	MP006-A-R-SD



3. Product Name List

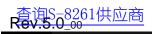
			Table	e 1				
Model No.	Overcharge detection voltage [Vcu]	Overcharge hysteresis voltage [V _{HC}]	Overdischarge detection voltage [V _{DL}]	Overdischarge hysteresis voltage [V _{HD}]	Overcurrent 1 detection voltage [V _{IOV1}]	0 V battery charge function	Delay time combi- nation ^{*1}	Power down function
S-8261AAGMD-G2GT2x	4.280 V	0.20 V	2.30 V	0 V	0.16 V	Available	(1)	Yes
S-8261AAHMD-G2HT2x	4.280 V	0.20 V	2.30 V	0 V	0.08 V	Available	(1)	Yes
S-8261A <mark>AJMD-G</mark> 2JT2x	4.325 V	0.25 V	2.50 V	0.4 V	0.15 V	Unavailable	(1)	Yes
S-8261AALMD-G2LT2x	4.300 V	0.10 V	2.30 V	0 V	0.08 V	Unavailable	(1)	Yes
S-8261AAMMD-G2MT2x	4.300 V	0.10 V	2.30 V	0 V	0.20 V	Unavailable	(1)	Yes
S-8261AANMD-G2NT2x	4.275 V	0.10 V	2.30 V	0.1 V	0.10 V	Available	(1)	Yes
S-8261AAOMD-G2OT2x	4.280 V	0.20 V	2.30 V	0 V	0.13 V	Unavailable	(1)	Yes
S-8261AAPMD-G2PT2x	4.325 V	0.25 V	2.50 V	0.4 V	0.10 V	Unavailable	(1)	Yes
S-8261AARMD-G2RT2x	4.280 V	0.20 V	2.30 V	0 V	0.10 V	Available	(1)	Yes
S-8261AASMD-G2ST2x	4.280 V	0.20 V	2.30 V	0 V	0.15 V	Unavailable	(2)	Yes
S-8261AATMD-G2TT2x	4.300 V	0.10 V	2.30 V	0 V	0.08 V	Available	(3)	Yes
S-8261AAUMD-G2UT2x	4.275 V	0.10 V	2.30 V	0.1 V	0.10 V	Available	(4)	Yes
S-8261AAXMD-G2XT2x	4.350 V	0.10 V	2.30 V	0.1 V	0.10 V	Available	(4)	Yes
S-8261AAZMD-G2ZT2x	4.280 V	0.25 V	2.50 V	0.4 V	0.10 V	Unavailable	(1)	Yes
S-8261ABAMD-G3AT2x	4.350 V	0.20 V	2.50 V	0 V	0.20 V	Available	(4)	Yes
S-8261ABBMD-G3BT2x	4.275 V	0.20 V	2.30 V	0 V	0.13 V	Available	(1)	Yes
S-8261ABCMD-G3CT2x	4.300 V	0.20 V	2.30 V	0 V	0.13 V	Available	(1)	Yes
S-8261ABIMD-G3IT2x	4.275 V	0.20 V	2.30 V	0 V	0.20 V	Unavailable	(5)	Yes
S-8261ABJMD-G3JT2x	4.280 V	0.20 V	3.00 V	0 V	0.08 V	Available	(1)	Yes
S-8261ABKMD-G3KT2x	4.100 V	0.25 V	2.50 V	0.4 V	0.15 V	Unavailable	(1)	Yes
S-8261ABLMD-G3LT2x	4.275 V	0.20 V	2.30 V	0 V	0.05 V	Unavailable	(5)	Yes
S-8261ABMMD-G3MT2x	4.280 V	0.20 V	2.80 V	0 V	0.10 V	Available	(1)	Yes
S-8261AB <mark>NMD-</mark> G3NT2x	4.300 V	0.20 V	2.30 V	0 V	0.06 V	Available	(1)	Yes
S-8261ABPMD-G3PT2x	4.200 V	0.10 V	2.80 V	0.1 V	0.15 V	Unavailable	(1)	Yes
S-8261ABRMD-G3RT2x	4.275 V	0.20 V	2.50 V	0.4 V	0.15 V	Unavailable	(1)	Yes
S-8261ABSMD-G3ST2x	4.280 V	0.10 V	2.50 V	0.5 V	0.18 V	Unavailable	(1)	Yes
S-8261ABTMD-G3TT2x	4.280 V	0.20 V	3.00 V	0.4 V	0.08 V	Available	(5)	Yes
S-8261ABYMD-G3YT2x	4.275 V	0.10 V	2.30 V	0.1 V	0.10 V	Available	(6)	Yes
S-8261ABZMD-G3ZT2x	4.325 V	0.25 V	2.50 V	0.4 V	0.15 V	Unavailable	(6)	Yes
S-8261ACAMD-G4AT2x	4.280 V	0.20 V	2.30 V	0 V	0.13 V	Unavailable	(6)	Yes
S-8261ACBMD-G4BT2x	4.250 V	0.20 V	2.60 V	0.3 V	0.12 V	Unavailable	(1)	No
S-8261ACDMD-G4DT2x	4.350 V	0.25 V	2.30 V	0.7 V	0.25 V	Available	(7)	Yes
S-8261ACEMD-G4ET2x	3.900 V	0.10 V	2.00 V	0.3 V	0.10 V	Available	(1)	Yes
S-8261ACFMD-G4FT2x	4.280 V	0.20 V	2.30 V	0 V	0.10 V	Available	(8)	Yes
S-8261ACHMD-G4HT2x	4.465 V	0.30 V	2.10 V	0 V	0.15 V	Available	(9)	Yes
S-8261ACIMD-G4IT2x	4.250 V	0.20 V	2.40 V	0.5 V	0.10 V	Available	(1)	No
S-8261ACJMD-G4JT2x	4.275 V	0.10 V	2.30 V	0.1 V	0.15 V	Available	(1)	Yes
S-8261ACKMD-G4KT2x	4.280 V	0.20 V	2.80 V	0 V	0.13 V	Available	(1)	Yes
S-8261ACMMD-G4MT2x	4.325 V	0.20 V	3.00 V	0.4 V	0.06 V	Unavailable	(1)	Yes
S-8261ACNMD-G4NT2x	4.215 V	0.10 V	2.30 V	0.1 V	0.13 V	Unavailable	(1)	Yes

*1. Refer to the Table 2 about the details of the delay time combinations (1) to (9).

Remark 1. Please contact our sales office for the products with detection voltage value other than those specified above.
2. x: G or U

3. Please select products of environmental code = U for Sn 100%, halogen-free products.





		I	Table 2		
Delay time combination	Overcharge detection delay time [tcu]	Overdischarge detection delay time [t _{DL}]	Overcurrent 1 detection delay time [tiov1]	Overcurrent 2 detection delay time [t _{IOV2}]	Load short-circuiting detection delay time [tshort]
(1)	1.2 s 👐	144 ms	9 ms	2.24 ms	320 μs
(2)	1.2 s	144 ms	4.5 ms	2.24 ms	320 μs
(3)	4.6 s	36 ms	18 ms	9 ms	320 μs
(4)	4.6 s	144 ms	9 ms	2.24 ms	320 μs
(5)	1.2 s	36 ms	9 ms	2.24 ms	320 μs
(6)	1.2 s	144 ms	9 ms	1.12 ms	320 μs
(7)	1.2 s	290 ms	18 ms	2.24 ms	320 μs
(8)	1.2 s	144 ms	18 ms	2.24 ms	320 μs
(9)	0.3 s	36 ms 🚽 😽	9 ms	1.12 ms	320 μs

Remark The delay times can be changed within the range listed Table 3. For details, please contact our sales office.

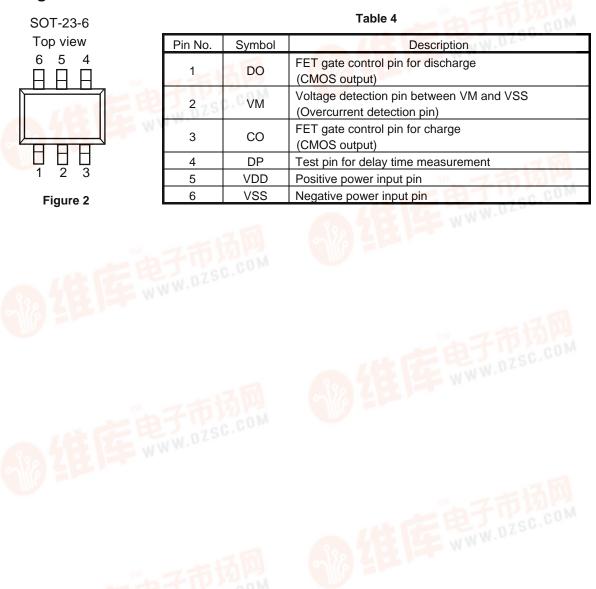
Table 3

	Table 3										
Delay time	Symbol	Se	election rang	е	Remarks						
Overcharge detection delay time	t _{CU}	0.15 s	1.2 s	4.6 s	Choose from the left.						
Overdischarge detection delay time	t _{DL}	36 ms	144 ms	290 ms	Choose from the left.						
Overcurrent 1 detection delay time	t _{IOV1}	4.5 ms	9 ms	18 ms	Choose from the left.						
Overcurrent 2 detection delay time	t _{IOV1}	1.12 ms	2.24 ms	N - W	Choose from the left.						
Load short-circuiting detection delay time	t SHORT	$-\gamma$	320 μs	600 μs	Choose from the left.						

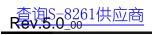
Remark The value surrounded by bold lines is the delay time of the standard products. WWW.DZSC



Pin Configuration







Absolute Maximum Ratings

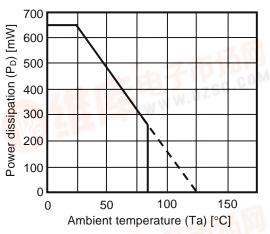
		l able 5		
			(Ta = 25°C unless otherwise	specifie
Item	Symbol	Applied pin	Absolute Maximum Ratings	Unit
Input voltage between VDD and VSS	V _{DS}	VDD	V _{SS} –0.3 to V _{SS} +12	V
Input pin voltage for VM	Vvm	VM	V _{DD} –28 to V _{DD} +0.3	V
Output pin voltage for CO	Vco	CO	V_{VM} –0.3 to $V_{\text{DD}}\text{+}0.3$	V
Output pin voltage for DO	V _{DO}	DO	V_{SS} –0.3 to V_{DD} +0.3	V
Dower dissinction	Р		250 (When not mounted on board)	mW
Power dissipation	PD	—	650 ^{*1}	mW
Operating ambient temperature	T _{opr}	_	-40 to +85	°C
Storage temperature	T _{stg}		-55 to +125	°C
 When mounted on board [Mounted board] 			WWW.DZSU.	

Tabla 6

- (1) Board size : 114.3 mm × 76.2 mm × t1.6 mm
- (2) Board name : JEDEC STANDARD51-7

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.





(2) When not mounted on board

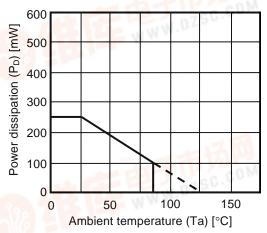


Figure 3 Power Dissipation of Package



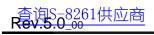
Electrical Characteristics

1. Except Detection Delay Time (25°C)

		Table 6			WWW	DZS	0	
				(la = 2	= 25°C unless otherwise spec			
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DETECTION VOLTAGE		DZSC. C						
Overcharge detection voltage	V _{CU}		V _{CU} -0.025	V _{CU}	V _{CU} +0.025	V	1	1
$V_{CU} = 3.9 \text{ V to } 4.4 \text{ V}, 5 \text{ mV Step}$	VCU	$Ta = -5^{\circ}C$ to $55^{\circ}C^{*1}$	V _{CU} -0.030	V _{CU}	V _{CU} +0.030	V	1	1
Overcharge hysteresis voltage $V_{HC} = 0.1 V$ to 0.4 V, 50 mV Step	V _{HC}	_	V _{HC} -0.025	V _{HC}	V _{HC} +0.025	V	0.C0M	1
Overdischarge detection voltage $V_{DL} = 2.0$ V to 3.0 V, 10 mV Step	V _{DL}	-15M M	V _{DL} -0.050	VDL	V _{DL} +0.050	V	2	2
Overdischarge hysteresis voltage V _{HD} = 0.0 V to 0.7 V, 100 mV Step	V _{HD}	DZSC.COM	V _{HD} -0.050	V_{HD}	V _{HD} +0.050	V	2	2
Overcurrent 1 detection voltage V _{IOV1} = 0.05 V to 0.3 V, 10 mV Step	VIOV1	_	V _{IOV1} -0.015	V_{IOV1}	V _{IOV1} +0.015	V	3	2
Overcurrent 2 detection voltage	V _{IOV2}		0.4	0.5	0.6	V	3	2
Load short-circuiting detection voltage	VSHORT		0.9	1.2	1.5	V	3	2
Charger detection voltage	V _{CHA}	_	-1.0	-0.7	-0.4	V	4	2
INPUT VOLTAGE, OPERATION VOLTAGE				22	WWW.	<i>V</i> -		
Operation voltage between VDD and VSS	V _{DSOP1}	Internal circuit operating voltage	1.5	12	8	V		
Operation voltage between VDD and VM	VDSOP2	Internal circuit operating voltage	1.5		28	V		
CURRENT CONSUMPTION (with power-d	<mark>own</mark> functi	on)						
Current consumption in normal operation	IOPE	$V_{DD}=3.5~V,~V_{VM}=0~V$	1.0	3.5	7.0	μA	5	2
Current consumption at power down	IPDN	$V_{DD} = V_{VM} = 1.5 \ V$			0.1	μA	5	2
CURRENT CONSUMPTION (without powe	er-down fu	nction)						
Current consumption in normal operation	I _{OPE}	$V_{DD}=3.5~V,~V_{VM}=0~V$	1.0	3.5	7.0	μA	5	2
Overdischarge current consumption	IOPED	$V_{DD} = V_{VM} = 1.5 \ V$	1.0	3.0	5.5	μA	5	2
OUTPUT RESISTANCE			12		- Will	DZS	0.0	
CO pin resistance "H"	RCOH	$V_{CO} = 3.0 \text{ V}, \text{ V}_{DD} = 3.5 \text{ V}, \text{ V}_{VM} = 0 \text{ V}$	2.5	5	10	kΩ	7	4
CO pin resistance "L"	R _{COL}	$V_{CO} = 0.5 \text{ V}, \text{ V}_{DD} = 4.5 \text{ V}, \text{ V}_{VM} = 0 \text{ V}$	2.5	5	10	kΩ	7	4
DO pin resistance "H"	RDOH	$V_{DO} = 3.0 \text{ V}, V_{DD} = 3.5 \text{ V}, V_{VM} = 0 \text{ V}$	2.5	5	10	kΩ	8	4
DO pin resistance "L"	RDOL	$V_{DO} = 0.5 \text{ V}, V_{DD} = V_{VM} = 1.8 \text{ V}$	2.5	5	10	kΩ	8	4
VM INTERNAL RESISTANCE	WWW							
Internal resistance between VM and VDD	R _{VMD}	$V_{DD} = 1.8 \text{ V}, V_{VM} = 0 \text{ V}$	100	300	900	kΩ	6	3
Internal resistance between VM and VSS	R_{VMS}	$V_{DD} = 3.5 \text{ V}, V_{VM} = 1.0 \text{ V}$	10	20	40	kΩ	6	3
0 V BATTERY CHARGING FUNCTION				-	-		212	
0 V battery charge starting charger voltage	V _{0CHA}	0 V battery charging available	1.2	_	2-1	V	11	2
0 V battery charge inhibition battery voltage	V _{0INH}	0 V battery charging unavailable	1-2		0.5	V	12	2

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.





2. Except Detection Delay Time (-40°C to +85°C^{*1})

		Table 7	′Ta = −40°	$^{\circ}C$ to +8!	5°C ^{*1} unle	ss oth	erwise sp	ecified
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DETECTION VOLTAGE	- 1	书切 牌	1					
Overcharge detection voltage $V_{CU} = 3.9$ V to 4.4 V, 5 mV Step	Vcu	DZSC.COM	V _{CU} -0.055	V _{CU}	V _{CU} +0.040	V	1	1
Overcharge hysteresis voltage $V_{HC} = 0.1 \text{ V to } 0.4 \text{ V}, 50 \text{ mV Step}$	V _{HC}		V _{HC} -0.025	V _{HC}	V _{HC} +0.025	V	1	1
Overdischarge detection voltage V _{DL} = 2.0 V to 3.0 V, 10 mV Step	V _{DL}	_	V _{DL} -0.080	V _{DL}	V _{DL} +0.080	V	2	2
Overdischarge hysteresis voltage $V_{HD} = 0.0 V$ to 0.7 V, 100 mV Step	V _{HD}	-	V _{HD} -0.050	V _{HD}	V _{HD} +0.050	0 VS	2	2
Overcurrent 1 detection voltage V _{IOV1} = 0.05 V to 0.3 V, 10 mV Step	V _{IOV1}	515M- 618	V _{IOV1} -0.021	VIOV1	V _{IOV1} +0.021	V	3	2
Overcurrent 2 detection voltage	V _{IOV2}	C COM	0.37	0.5	0.63	V	3	2
Load short-circuiting detection voltage	VSHORT	07501	0.7	1.2	1.7	V	3	2
Charger detection voltage	V _{CHA}		-1.2	-0.7	-0.2	V	4	2
INPUT VOLTAGE, OPERATION VOLTAGE							-	
Operation voltage between VDD and VSS	V _{DSOP1}	Internal circuit operating voltage	1.5		8	V		
Operation voltage between VDD and VM	V _{DSOP2}	Internal circuit operating voltage	1.5		28	V	COM	_
CURRENT CONSUMPTION (with power-d	own functi	on)	162		W IN	025		
Current consumption in normal operation	I _{OPE}	$V_{DD} = 3.5 \text{ V}, \text{ V}_{VM} = 0 \text{ V}$	0.7	3.5	8.0	μΑ	5	2
Current consumption at power down	I _{PDN}	$V_{DD} = V_{VM} = 1.5 \text{ V}$		_	0.1	μΑ	5	2
CURRENT CONSUMPTION (without powe	e <mark>r-down f</mark> u	nction)						
Current consumption in normal operation	IOPE	$V_{DD}=3.5~V,~V_{VM}=0~V$	0.7	3.5	8.0	μΑ	5	2
Overdischarge current consumption	IOPED	$V_{DD} = V_{VM} = 1.5 \ V$	0.7	3.0	6.0	μΑ	5	2
OUTPUT RESISTANCE	-i	.			i			
CO pin resistance "H"	R _{COH}	$V_{CO} = 3.0 \text{ V}, V_{DD} = 3.5 \text{ V}, V_{VM} = 0 \text{ V}$	1.2	5	15	kΩ	7	4
CO pin resistance "L"	R_{COL}	$V_{CO} = 0.5 \text{ V}, V_{DD} = 4.5 \text{ V}, V_{VM} = 0 \text{ V}$	1.2	5	15	kΩ	7	4
DO pin resistance "H"	R _{DOH}	$V_{DO} = 3.0 \text{ V}, V_{DD} = 3.5 \text{ V}, V_{VM} = 0 \text{ V}$	1.2	5	15	kΩ	8	4
DO pin resistance "L"	R _{DOL}	$V_{DO} = 0.5 \text{ V}, V_{DD} = V_{VM} = 1.8 \text{ V}$	1.2	5	15	kΩ	8	4
VM INTERNAL RESISTANCE								
Internal resistance between VM and VDD	R _{VMD}	$V_{DD} = 1.8 \text{ V}, V_{VM} = 0 \text{ V}$	78	300	1310	kΩ	6	3
Internal resistance between VM and VSS	R _{VMS}	$V_{DD} = 3.5 \text{ V}, V_{VM} = 1.0 \text{ V}$	7.2	20	44	kΩ	6	3
0 V BATTERY CHARGING FUNCTION	WWW	U L L						
0 V battery charge starting charger voltage	V _{0CHA}	0 V battery charging available	1.7			V	11	2
0 V battery charge inhibition battery voltage	V _{0INH}	0 V battery charging unavailable			0.3	V	12	2

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.



3. Detection Delay Time

(1) S-8261AAG, S-8261AAH, S-8261AAJ, S-8261AAL, S-8261AAM, S-8261AAN, S-8261AAO, S-8261AAP, S-8261AAR, S-8261AAZ, S-8261ABB, S-8261ABC, S-8261ABJ, S-8261ABK, S-8261ABM, S-8261ABR, S-8261ABR, S-8261ABS, S-8261ACB, S-8261ACE, S-8261ACI, S-8261ACK, S-8261ACM, S-8261ACJ, S-8261ACN

		Table 8						
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)								
Overcharge detection delay time	t _{CU}		0.96	1.2	1.4	S	9	5
Overdischarge detection delay time	t _{DL}		115	144	173	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		7.2	9	11	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.8	2.24	2.7	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		220	320	380	μs	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}	-1.3							
Overcharge detection delay time	t _{CU}	MOQUE	0.7	1.2	2.0	s	9	5
Overdischarge detection delay time	t _{DL}		80	144	245	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		5	9	15	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.2	2.24	3.8	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		150	320	540	μS	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.

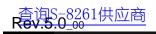
(2) S-8261AAS

Table 9

ltem	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DELAY TI <mark>ME</mark> (Ta = 25°C)							17.60	
Overcharge detection delay time	t _{CU}		0.96	1.2	1.4	S	9	5
Overdischarge detection delay time	t _{DL}	_	115	144	173	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		3.6	4.5	5.4	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.8	2.24	2.7	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		220	320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}		COM						
Overcharge detection delay time	t _{cu}		0.7	1.2	2.0	S	9	5
Overdischarge detection delay time	t _{DL}	_	80	144	245	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		2.5	4.5	7.7	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.2	2.24	3.8	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		150	320	540	μs	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.





(3) S-8261AAT

		Table 10						
ltem	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)	100	-151 M	22					
Overcharge detection delay time	t _{CU}	COM -	3.7	4.6	5.5	S	9	5
Overdischarge detection delay time	t _{DL}	LSC.00	29	36	43	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		14	18	22	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	_	7.2	9	11	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		220	320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}				10	-	1	101	
Overcharge detection delay time	t _{CU}	_	2.5	4.6	7.8	S	9	5
Overdischarge detection delay time	t _{DL}		20	36	61	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	- 190	10	18	31	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		5	9	15	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	- MOD	150	320	540	μS	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.

(4) S-8261AAU, S-8261AAX, S-8261ABA

Table 11

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)	27							
Overcharge detection delay time	t _{CU}	SC.CUM	3.7	4.6	5.5	S	9	5
Overdischarge detection delay time	t _{DL}		115	144	173	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		7.2	9	11	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.8	2.24	2.7	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	_	220	320	380	μs	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}				-	51	-112	CON	1
Overcharge detection delay time	t _{CU}	_	2.5	4.6	7.8	S	9	5
Overdischarge detection delay time	t _{DL}		80	144	245	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		5	9	15	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	COM -	1.2	2.24	3.8	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	LSC.COM_	150	320	540	μs	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.



(5) S-8261ABI, S-8261ABL, S-8261ABT

		Table 12						
Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test condition	Test circuit
DELAY TIME (Ta = 25°C)	1	5111 916						
Overcharge detection delay time	t _{CU}	COM -	0.96	1.2	1.4	s	9	5
Overdischarge detection delay time	t _{DL}	0.00	29	36	43	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	_	7.2	9	11	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	—	1.8	2.24	2.7	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	—	220	320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) *1				10	5 -1		17	
Overcharge detection delay time	t _{CU}	—	0.7	1.2	2.0	s	9	5
Overdischarge detection delay time	t _{DL}		20	36	61	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	- 120	5	9	15	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.2	2.24	3.8	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	- M02 -	150	320	540	μS	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.

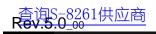
(6) S-8261ABY, S-8261ABZ, S-8261ACA

Table 13

ltem	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)	2-1							
Overcharge detection delay time	t _{CU}	SC.CUM	0.96	1.2	1.4	s	9	5
Overdischarge detection delay time	t _{DL}		115	144	173	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	_	7.2	9	11	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	_	0.89	1.12	1.35	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	_	220	320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) *1				-	21	-112	CON	
Overcharge detection delay time	t _{CU}	_	0.7	1.2	2.0	S	9	5
Overdischarge detection delay time	t _{DL}		80	144	245	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		5	9	15	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	COM -	0.61	1.12	1.91	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	LSC.00 _	150	320	540	μS	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.





(7) S-8261ACD

		Table 14						
ltem	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)	100	15111 916		P				
Overcharge detection delay time	t _{cu}	coM -	0.96	1.2	1.4	S	9	5
Overdischarge detection delay time	t _{DL}		232	290	348	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	—	14	18	22	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.8	2.24	2.7	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		220	320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}				10	1	1	1214	
Overcharge detection delay time	t _{CU}		0.7	1.2	2.0	s	9	5
Overdischarge detection delay time	t _{DL}	-	160	290	493	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}		10	18	31	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		1.2	2.24	3.8	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	- MO2	150	320	540	μS	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.

Table 15

(8) S-8261ACF

						07	5.4.	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)	27							
Overcharge detection delay time			0.96	1.2	1.4	S	9	5
Overdischarge detection delay time	t _{DL}	_	115	144	173	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}			18	22	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	_		2.24	2.7	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	_		320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}				-	24	-11	CON	
Overcharge detection delay time	t _{CU}		0.7	1.2	2.0	S	9	5
Overdischarge detection delay time	t _{DL}		80	144	245	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	15111 - M61	10	18	31	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}	and -	1.2	2.24	3.8	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	50.00	150	320	540	μs	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.



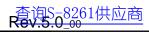
LOW DROPOUT CMOS VOLTAGE REGULATOR S 8261 Series

(9) S-8261ACH

		Table 16						
Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Test Condition	Test Circuit
DELAY TIME (Ta = 25°C)	100	1311 961						
Overcharge detection delay time	t _{CU}	SOM -	0.24	0.3	0.36	S	9	5
Overdischarge detection delay time	t _{DL}	50.00	29	36	43	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	V1 —		9	11	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}			1.12	1.35	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}		220	320	380	μS	10	5
DELAY TIME (Ta = -40°C to +85°C) ^{*1}				10	1		1214	
Overcharge detection delay time	t _{CU}		0.17	0.3	0.51	S	9	5
Overdischarge detection delay time	t _{DL}		20	36	61	ms	9	5
Overcurrent 1 detection delay time	t _{IOV1}	120	5	9	15	ms	10	5
Overcurrent 2 detection delay time	t _{IOV2}		0.61	1.12	1.91	ms	10	5
Load short-circuiting detection delay time	t _{SHORT}	COM -	150	320	540	μS	10	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.





Test Circuits

Caution Unless otherwise specified, the output voltage levels "H" and "L" at CO pin (V_{CO}) and DO pin (V_{DO}) are judged by the threshold voltage (1.0 V) of the N-channel FET. Judge the CO pin level with respect to V_{VM} and the DO pin level with respect to V_{SS}.

(1) Test Condition 1, Test Circuit 1

(Overcharge Detection Voltage, Overcharge Hysteresis Voltage)

The overcharge detection voltage (V_{CU}) is defined as the voltage between VDD and VSS at which V_{CO} goes from "H" to "L" when the voltage V1 is gradually increased from the starting condition of V1 = 3.5 V. The overcharge hysteresis voltage (V_{HC}) is then defined as the difference between the overcharge detection voltage (V_{CU}) and the voltage between VDD and VSS at which V_{CO} goes from "L" to "H" when the voltage V1 is gradually decreased.

(2) Test Condition 2, Test Circuit 2

(Overdischarge Detection Voltage, Overdischarge Hysteresis Voltage)

The overdischarge detection voltage (V_{DL}) is defined as the voltage between VDD and VSS at which V_{DO} goes from "H" to "L" when the voltage V1 is gradually decreased from the starting condition of V1 = 3.5 V and V2 = 0 V. The overdischarge hysteresis voltage (V_{HD}) is then defined as the difference between the overdischarge detection voltage (V_{DL}) and the voltage between VDD and VSS at which V_{DO} goes from "L" to "H" when the voltage V1 is gradually increased.

(3) Test Condition 3, Test Circuit 2

(Overcurrent 1 Detection Voltage, Overcurrent 2 Detection Voltage, Load Short-Circuiting Detection Voltage) The overcurrent 1 detection voltage (V_{IOV1}) is defined as the voltage between VM and VSS whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 1 detection delay time when the voltage V2 is increased rapidly (within 10 µs) from the starting condition V1 = 3.5 V and V2 = 0 V. The overcurrent 2 detection voltage (V_{IOV2}) is defined as the voltage between VM and VSS whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 2 detection delay time when the voltage V2 is increased rapidly (within 10 µs) from the starting condition V1 = 3.5 V and V2 = 0 V. The load short-circuiting detection voltage (V_{SHORT}) is defined as the voltage between VM and VSS whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the load short-circuiting detection delay time when the voltage V2 is increased rapidly (within 10 µs) from the starting condition V1 = 3.5 V and V2 = 0 V. The load short-circuiting detection voltage (V_{SHORT}) is defined as the voltage between VM and VSS whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the load short-circuiting detection delay time when the voltage V2 is increased rapidly (within 10 µs) from the starting condition V1 = 3.5 V and V2 = 0 V.

(4) Test Condition 4, Test Circuit 2

(Charger Detection Voltage, Abnormal Charge Current Detection Voltage)

The charger detection voltage (V_{CHA}) is defined as the voltage between VM and VSS at which V_{DO} goes from "L" to "H" when the voltage V2 is gradually decreased from 0 V after the voltage V1 is gradually increased from the starting condition of V1 = 1.8 V and V2 = 0 V until the voltage V1 becomes V1 = $V_{DL} + (V_{HD} / 2)$.

The charger detection voltage can be measured only in the product whose overdischarge hysteresis $V_{HD} \neq 0$. Set V1 = 3.5 V and V2 = 0 V. Decrease V2 from 0 V gradually. The voltage between VM and VSS when V_{CO} goes from "H" to "L" is the abnormal charge current detection voltage. The abnormal charge current detection voltage has the same value as the charger detection voltage (V_{CHA}).

(5) Test Condition 5, Test Circuit 2

(Normal Operation Current Consumption, Power-Down Current Consumption, Overdischarge Current Consumption)

For products with power-down function

The operating current consumption (I_{OPE}) is the current that flows through the VDD pin (I_{DD}) under the set conditions of V1 = 3.5 V and V2 = 0 V (Normal status).

The power-down current consumption (I_{PDN}) is the current that flows through the VDD pin (I_{DD}) under the set conditions of V1 = V2 = 1.5 V (Overdischarge status).

For products without power-down function

The operating current consumption (I_{OPE}) is the current that flows through the VDD pin (I_{DD}) under the set conditions of V1 = 3.5 V and V2 = 0 V (Normal status).

The Overdischarge current consumption (I_{OPED}) is the current that flows through the VDD pin (I_{DD}) under the set conditions of V1 = V2 = 1.5 V (Overdischarge status).

(6) Test Condition 6, Test Circuit 3

(Internal Resistance between VM and VDD, Internal Resistance between VM and VSS)

The resistance between VM and VDD (R_{VMD}) is the internal resistance between VM and VDD under the set conditions of V1 = 1.8 V and V2 = 0 V.

The resistance between VM and VSS (R_{VMS}) is the internal resistance between VM and VSS under the set conditions of V1 = 3.5 V and V2 = 1.0 V.

(7) Test Condition 7, Test Circuit 4

(CO Pin Resistance "H", CO Pin Resistance "L")

The CO pin resistance "H" (R_{COH}) is the resistance the CO pin under the set condition of V1 = 3.5 V, V2 = 0 V and V3 = 3.0 V.

The CO pin resistance "L" (R_{COL}) is the resistance the CO pin under the set condition of V1 = 4.5 V, V2 = 0 V and V3 = 0.5 V.

(8) Test Condition 8, Test Circuit 4

(DO Pin Resistance "H", DO Pin Resistance "L")

The DO pin resistance "H" (R_{DOH}) is the resistance the DO pin under the set condition of V1 = 3.5 V, V2 = 0 V and V4 = 3.0 V.

The DO pin resistance "L" (R_{DOL}) is the resistance the DO pin under the set condition of V1 = 1.8 V, V2 = 0 V and V4 = 0.5 V.

(9) Test Condition 9, Test Circuit 5

(Overcharge Detection Delay Time, Overdischarge Detection Delay Time)

The overcharge detection delay time (t_{CU}) is the time needed for V_{CO} to change from "H" to "L" just after the voltage V1 momentarily increases (within 10 μ s) from the overcharge detection voltage (V_{CU}) – 0.2 V to the overcharge detection voltage (V_{CU}) + 0.2 V under the set condition of V2 = 0 V.

The overdischarge detection delay time (t_{DL}) is the time needed for V_{DO} to change from "H" to "L" just after the voltage V1 momentarily decreases (within 10 µs) from the overdischarge detection voltage (V_{DL}) +0.2 V to the overdischarge detection voltage (V_{DL}) – 0.2 V under the set condition of V2 = 0 V.

(10) Test Condition 10, Test Circuit 5

(Overcurrent 1 Detection Delay Time, Overcurrent 2 Detection Delay Time, Load Short-circuiting Detection Delay Time, Abnormal Charge Current Detection Delay Time)

The overcurrent 1 detection delay time (t_{IOV1}) is the time needed for V_{DO} to go "L" after the voltage V2 momentarily increases (within 10 μ s) from 0 V to 0.35 V under the set condition of V1 = 3.5 V and V2=0 V.

The overcurrent 2 detection delay time (t_{IOV2}) is the time needed for V_{DO} to go "L" after the voltage V2 momentarily increases (within 10 μ s) from 0 V to 0.7 V under the set condition of V1 = 3.5 V and V2 = 0 V.

The load short-circuiting detection delay time (t_{SHORT}) is the time needed for V_{DO} to go "L" after the voltage V2 momentarily increases (within 10 µs) from 0 V to 1.6 V under the set condition of V1 = 3.5 V and V2 = 0 V.

The abnormal charge current detection delay time is the time needed for V_{CO} to go from "H" to "L" after the voltage V2 momentarily decreases (within 10 µs) from 0 V to –1.1 V under the set condition of V1 = 3.5 V and V2 = 0 V. The abnormal charge current detection delay time has the same value as the overcharge detection delay time.

(11) Test Condition 11, Test Circuit 2 (Product with 0 V battery charge function)

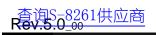
(0 V Battery Charge Starting Charger Voltage)

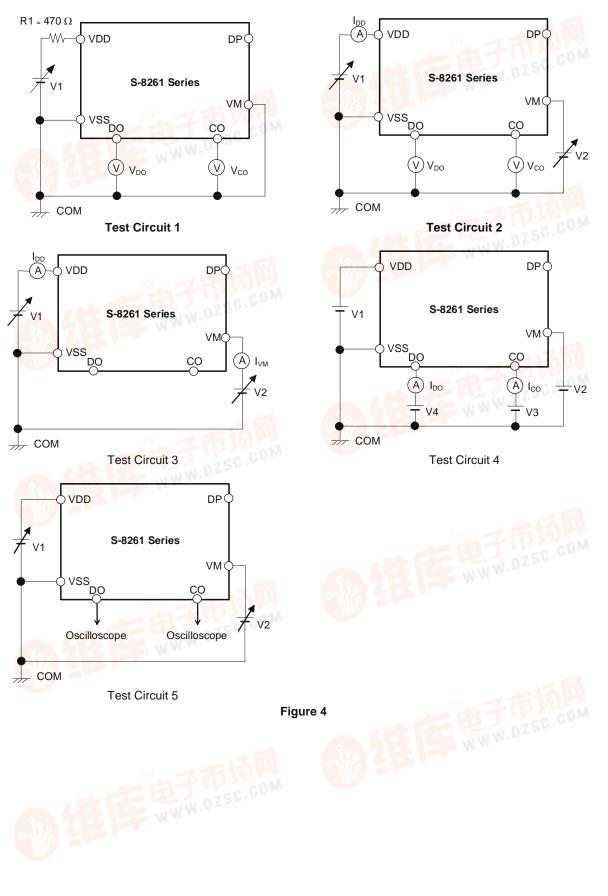
The 0 V battery charge starting charger voltage (V_{0CHA}) is defined as the voltage between VDD and VM at which V_{CO} goes "H" (V_{VM} + 0.1 V or higher) when the voltage V2 is gradually decreased from the starting condition of V1 = V2 = 0 V.

(12) Test Condition 12, Test Circuit 2 (Product with 0 V battery charge inhibition function) (0 V Battery Charge Inhibition Battery Voltage)

The 0 V battery charge inhibition battery voltage (V_{0INH}) is defined as the voltage between VDD and VSS at which V_{CO} goes "H" (V_{VM} + 0.1 V or higher) when the voltage V1 is gradually increased from the starting condition of V1 = 0 V and V2 = -4 V.









Operation

Remark Refer to "Battery Protection IC Connection Example".

1. Normal Status

The S-8261 Series monitors the voltage of the battery connected between VDD pin and VSS pin and the voltage difference between VM pin and VSS pin to control charging and discharging. When the battery voltage is in the range from the overdischarge detection voltage (V_{DL}) to the overcharge detection voltage (V_{CU}), and the VM pin voltage is in the range from the charger detection voltage (V_{CHA}) to the overcurrent 1 detection voltage (V_{IOV1}), the IC turns both the charging and discharging control FETs on. This status is called the normal status, and in this status charging and discharging can be carried out freely.

Caution When a battery is connected to the IC for the first time, discharging may not be enabled. In this case, short the VM pin and VSS pin or connect the charger to restore the normal condition.

2. Overcurrent Status (Detection of Overcurrent 1, Overcurrent 2 and Load Short-circuiting)

When a battery in the normal status is in the status where the voltage of the VM pin is equal to or higher than the overcurrent detection voltage because the discharge current is higher than the specified value and the status lasts for the overcurrent detection delay time, the discharge control FET is turned off and discharging is stopped. This status is called the overcurrent status.

In the overcurrent status, the VM and VSS pins are shorted by the resistor between VM and VSS (R_{VMS}) in the IC. However, the voltage of the VM pin is at the V_{DD} potential due to the load as long as the load is connected. When the load is disconnected, the VM pin returns to the V_{SS} potential.

This IC detects the status when the impedance between the EB+ pin and EB- pin (Refer to **Figure 10**) increases and is equal to the impedance that enables automatic restoration and the voltage at the VM pin returns to overcurrent 1 detection voltage (V_{IOV1}) or lower and the overcurrent status is restored to the normal status.

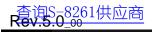
Caution The impedance that enables automatic restoration varies depending on the battery voltage and the set value of overcurrent 1 detection voltage.

3. Overcharge Status

When the battery voltage becomes higher than the overcharge detection voltage (V_{CU}) during charging under the normal status and the detection continues for the overcharge detection delay time (t_{CU}) or longer, the S-8261 Series turns the charging control FET off to stop charging. This status is called the overcharge status. The overcharge status is released by the following two cases ((1) and (2)):

- (1) When the battery voltage falls below the overcharge release voltage (V_{CU}) overcharge detection hysteresis voltage (V_{HC}), the S-8261 Series turns the charging control FET on and turns to the normal status.
- (2) When a load is connected and discharging starts, the S-8261 Series turns the charging control FET on and returns to the normal status. Just after the load is connected and discharging starts, the discharging current flows through the parasitic diode in the charging control FET. At this moment the VM pin potential becomes V_f, the voltage for the parasitic diode, higher than V_{SS} level. When the battery voltage goes under the overcharge detection voltage (V_{CU}) and provided that the VM pin voltage is higher than the overcurrent 1 detection voltage, the S-8261 Series releases the overcharge status.
- Caution 1. If the battery is charged to a voltage higher than the overcharge detection voltage (V_{CU}) and the battery voltage does not fall below the overcharge detection voltage (V_{CU}) even when a heavy load is connected, the detection of overcurrent 1, overcurrent 2 and load short-circuiting do not function until the battery voltage falls below overcharge detection voltage (V_{CU}). Since an actual battery has an internal impedance of several dozens of m Ω , the battery voltage drops immediately after a heavy load that causes overcurrent is connected, and the detection of overcurrent 1, overcurrent 2 and load short-circuiting function.
 - 2. When a charger is connected after the overcharge detection, the overcharge status is not released even if the battery voltage is below the overcharge release voltage (V_{CL}). The overcharge status is released when the VM pin voltage goes over the charger detection voltage (V_{CHA}) by removing the charger.





4. Overdischarge Status

For products with power-down function

When the battery voltage falls below the overdischarge detection voltage (V_{DL}) during discharging under the normal status and the detection continues for the overdischarge detection delay time (t_{DL}) or longer, the S-8261 Series turns the discharging control FET off to stop discharging. This status is called the overdischarge status. When the discharging control FET is turned off, the VM pin voltage is pulled up by the resistor between VM and VDD in the IC (R_{VMD}). When the voltage difference between the VM and VDD then is 1.3 V (typ.) or lower, the current consumption is reduced to the power-down current consumption (I_{PDN}). This status is called the power-down status.

The power-down status is released when a charger is connected and the voltage difference between the VM and VDD becomes 1.3 V (typ.) or higher. Moreover when the battery voltage becomes the overdischarge detection voltage (V_{DL}) or higher, the S-8261 Series turns the discharging FET on and returns to the normal status.

For products without power-down function

When the battery voltage falls below the overdischarge detection voltage (V_{DL}) during discharging under the normal status and the detection continues for the overdischarge detection delay time (t_{DL}) or longer, the S-8261 Series turns the discharging control FET off to stop discharging. This status is called the overdischarge status. When the discharging control FET is turned off, the VM pin voltage is pulled up by the resistor between VM and VDD in the IC (R_{VMD}).

When the battery voltage becomes the overdischarge detection voltage (V_{DL}) or higher, the S-8261 Series turns the discharging FET on and returns to the normal status.

5. Charger Detection

When a battery in the overdischarge status is connected to a charger and provided that the VM pin voltage is lower than the charger detection voltage (V_{CHA}), the S-8261 Series releases the overdischarge status and turns the discharging control FET on when the battery voltage becomes equal to or higher than the overdischarge detection voltage (V_{DL}) since the charger detection function works. This action is called charger detection.

When a battery in the overdischarge status is connected to a charger and provided that the VM pin voltage is not lower than the charger detection voltage (V_{CHA}), the S-8261 Series releases the overdischarge status when the battery voltage reaches the overdischarge detection voltage (V_{DL}) + overdischarge hysteresis (V_{HD}) or higher.

6. Abnormal Charge Current Detection

If the VM pin voltage falls below the charger detection voltage (V_{CHA}) during charging under normal status and it continues for the overcharge detection delay time (t_{CU}) or longer, the charging control FET turns off and charging stops. This action is called the abnormal charge current detection.

Abnormal charge current detection works when the DO pin voltage is "H" and the VM pin voltage falls below the charger detection voltage (V_{CHA}). Consequently, if an abnormal charge current flows to an over-discharged battery, the S-8261 Series turns the charging control FET off and stops charging after the battery voltage becomes higher than the overdischarge detection voltage which make the DO pin voltage "H", and still after the overcharge detection delay time (t_{CU}) elapses.

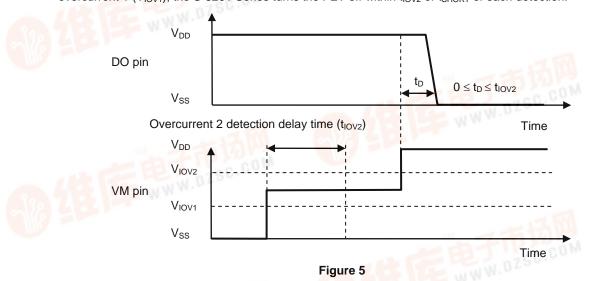
Abnormal charge current detection is released when the voltage difference between VM pin and VSS pin becomes less than charger detection voltage (V_{CHA}).



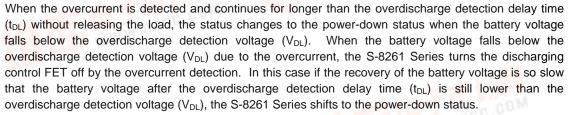
7. Delay Circuits

The detection delay times are determined by dividing a clock of the approximately 3.5 kHz with the counter.

Remark 1. The detection delay time for overcurrent 2 (t_{IOV2}) and load short-circuiting (t_{SHORT}) start when the overcurrent 1 (V_{IOV1}) is detected. When the overcurrent 2 (V_{IOV2}) or load short-circuiting (V_{SHORT}) is detected over the detection delay time for each of them (= t_{IOV2} or t_{SHORT}) after the detection of overcurrent 1 (V_{IOV1}), the S-8261 Series turns the FET off within t_{IOV2} or t_{SHORT} of each detection.



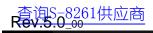
2. For products with power-down function



For products without power-down function

When the overcurrent is detected and continues for longer than the overdischarge detection delay time (t_{DL}) without released the load, the status changes to the overdischarge status when the battery voltage falls below overdischarge detection voltage (V_{DL}) . When the battery voltage falls below overdischarge detection voltage (V_{DL}) due to the overcurrent, the S-8261 Series turns the discharging control FET off by the overcurrent detection. In this case, if the recovery of the battery voltage is so slow that the battery voltage after the overdischarge detection delay time (t_{DL}) is still lower than the overdischarge detection voltage (V_{DL}) , S-8261 Series shifts to the overdischarge status.





8. DP Pin

The DP pin is a test pin for delay time measurement and it should be open in the actual application. If a capacitor whose capacitance is larger than 1000 pF or a resistor whose resistance is less than $1 M\Omega$ is connected to this pin, error may occur in the delay times or in the detection voltages.

9. 0 V Battery Charging Function "Available"

This function is used to recharge the connected battery whose voltage is 0 V due to the self-discharge. When the 0 V battery charge starting charger voltage (V_{0CHA}) or higher is applied between EB+ pin and EB- pin by connecting a charger, the charging control FET gate is fixed to VDD pin voltage. When the voltage between the gate and source of the charging control FET becomes equal to or higher than the turn-on voltage due to the charger voltage, the charging control FET is turned on to start charging. At this time, the discharging control FET is off and the charging current flows through the internal parasitic diode in the discharging control FET. When the battery voltage becomes equal to or higher than the overdischarge hysteresis voltage (V_{HD}), the S-8261 Series enters the normal status.

- Caution Some battery providers do not recommend charging for completely self-discharged battery. Please ask battery providers before determine whether to enable or inhibit the 0 V battery charging function.
- **Remark** The 0 V battery charge function has higher priority than the abnormal charge current detection function. Consequently, a product with the 0 V battery charging function is enabled charges a battery forcibly and abnormal charge current cannot be detected when the battery voltage is low.

10. 0 V Battery Charging Function "Unavailable"

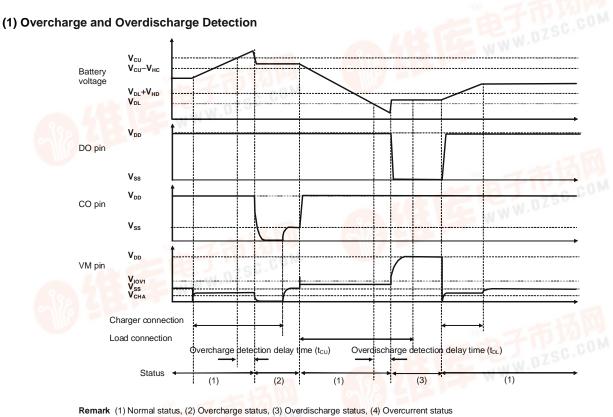
This function inhibits the recharging when a battery that is short-circuited (0 V battery) internally is connected. When the battery voltage is the 0 V battery charge inhibition battery voltage (V_{OINH}) or lower, the charging control FET gate is fixed to EB- pin voltage to inhibit charging. When the battery voltage is the 0 V battery charge inhibition battery voltage (V_{OINH}) or lower, the charging control FET gate voltage (V_{OINH}) or higher, charging can be performed.

Caution Some battery providers do not recommend charging for completely self-discharged battery. Please ask battery providers before determining the 0 V battery charging function.



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Timing Chart



The charger is supposed to charge with constant current.



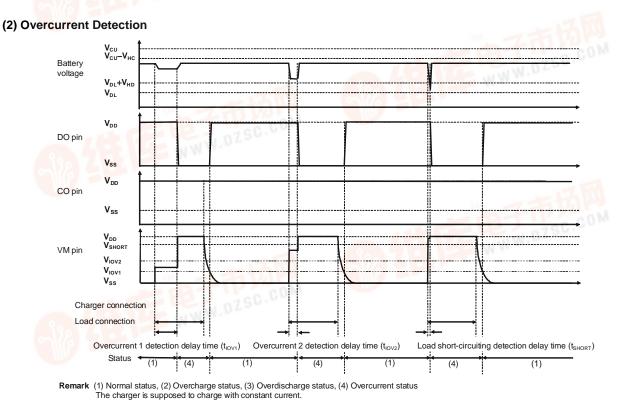
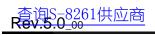


Figure 7





LOW DROPOUT CMOS VOLTAGE REGULATOR S-8261 Series

(3) Charger Detection

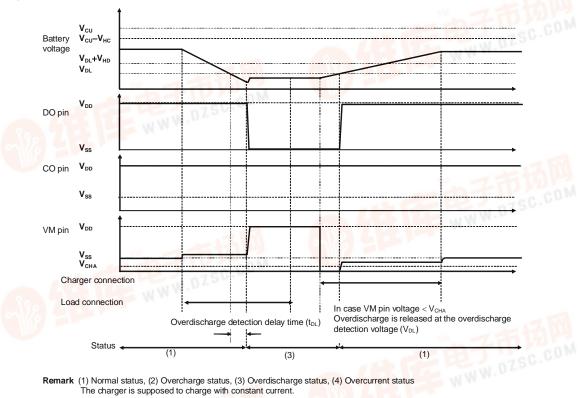
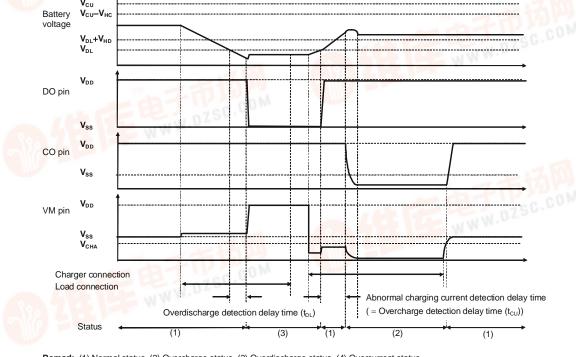


Figure 8

Vcu Battery V_{CU}-V_H voltage V_{DL}+V_{HD} VDL VDD DO pin Vss VDD CO pin V_{ss}

(4) Abnormal Charge Current Detection



Remark (1) Normal status, (2) Overcharge status, (3) Overdischarge status, (4) Overcurrent status The charger is supposed to charge with constant current.



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Figure 9

Battery Protection IC Connection Example

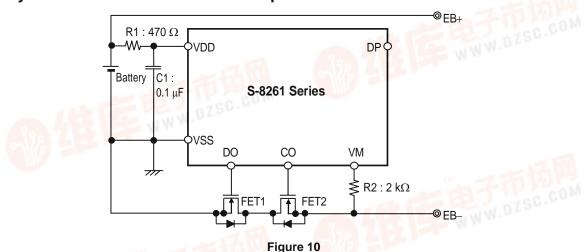


Table 17 Constant for External Components

Symbol	Part	Purpose	Тур.	Min.	Max.	Remarks
FET1	N-channel MOS FET	Discharge control	_	_	_	Threshold voltage \leq Overdischarge detection voltage ^{*1} Gate to source withstanding voltage \geq Charger voltage ^{*2}
FET2	N-channel MOS FET	Charge control		_	-	Threshold voltage \leq Overdischarge detection voltage ^{*1} Gate to source withstanding voltage \geq Charger voltage ^{*2}
R1	Resistor	ESD protection, For power fluctuation	470 Ω	300 Ω	1 kΩ 🕤	Resistance should be as small as possible to avoid lowering of the overcharge detection accuracy caused by VDD pin current. ³
C1	Capacitor	For power fluctuation	0.1 μF	0.022 μF	1.0 μF	Install a capacitor of 0.022 μF or higher between VDD and VSS. $^{\text{*4}}$
R2	Resistor	Protection for reverse connection of a charger	2 kΩ	300 Ω	4 kΩ	Select a resistance as large as possible to prevent large current when a charger is connected in reverse. ^{*5}

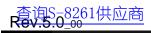
*1. If the threshold voltage of an FET is low, the FET may not cut the charging current. If an FET with a threshold voltage equal to or higher than the overdischarge detection voltage is used, discharging may be stopped before overdischarge is detected.

- *2. If the withstanding voltage between the gate and source is lower than the charger voltage, the FET may be destroyed.
- *3. If R1 has a high resistance, the voltage between VDD and VSS may exceed the absolute maximum rating when a charger is connected in reverse since the current flows from the charger to the IC. Insert a resistor of 300 Ω or higher to R1 for ESD protection.
- *4. If a capacitor of less than 0.022 μF is connected to C1, DO may oscillate when load short-circuiting is detected. Be sure to connect a capacitor of 0.022 μF or higher to C1.
- *5. If R2 has a resistance higher than 4 k Ω , the charging current may not be cut when a high-voltage charger is connected.

Caution 1. The above constants may be changed without notice.

- 2. The DP pin should be open.
- 3. It has not been confirmed whether the operation is normal or not in circuits other than the above example of connection. In addition, the example of connection shown above and the constant do not guarantee proper operation. Perform through evaluation using the actual application to set the constant.





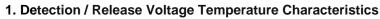
Precautions

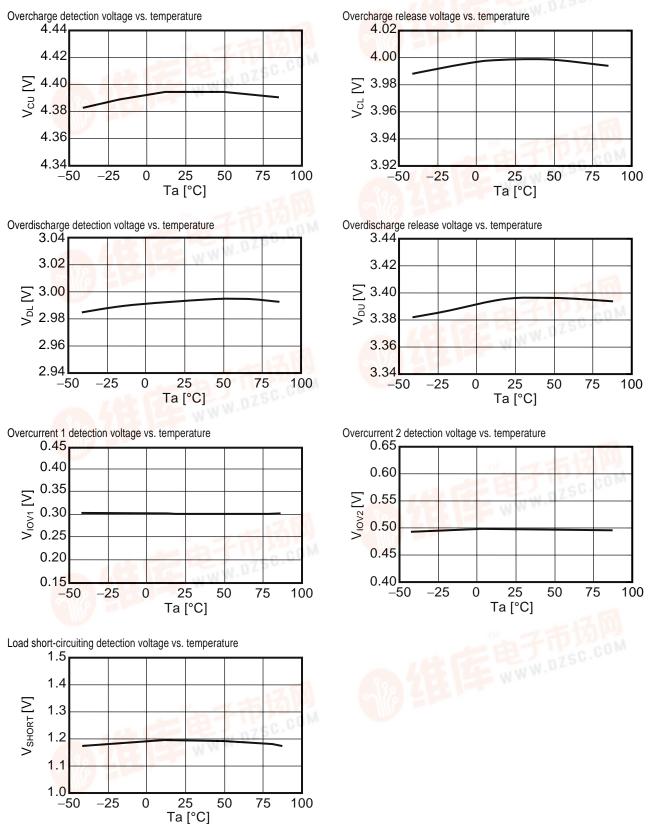
- The application conditions for the input voltage, output voltage, and load current should not exceed the package power dissipation.
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic protection circuit.
- SII claims no responsibility for any and all disputes arising out of or in connection with any infringement by products including this IC of patents owned by a third party.



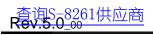
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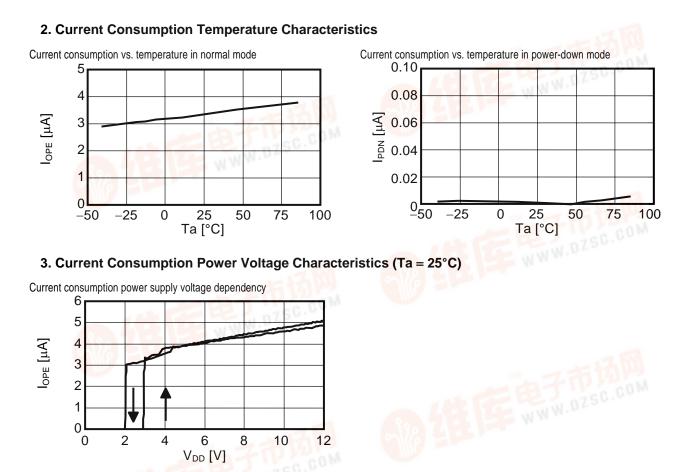






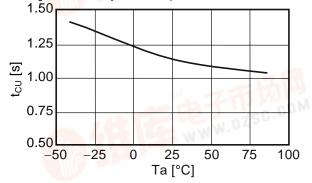


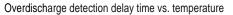


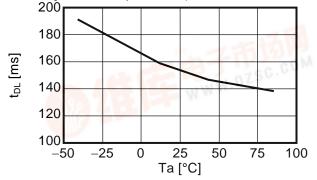


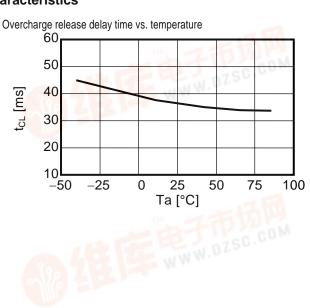
4. Detection / Release Delay Time Temperature Characteristics

Overcharge detection delay time vs. temperature

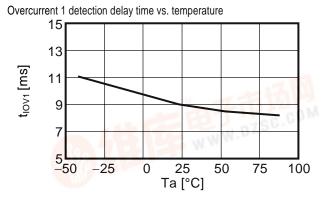


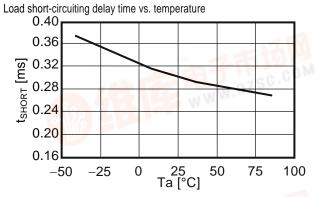






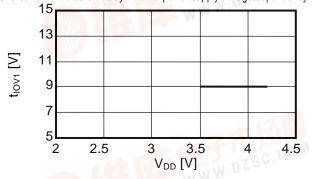


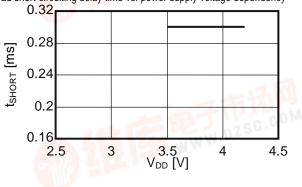




5. Delay Time Power-Voltage Characteristics (Ta = 25°C)

Overcurrent 1 detection delay time vs. power supply voltage dependency





Load short-circuiting delay time vs. power supply voltage dependency

Overcurrent 2 detection delay time vs. power supply voltage dependency

Overcurrent 2 detection delay time vs. temperature

-25

0

25

Ta [°C]

50

75

100

3.4

3.0

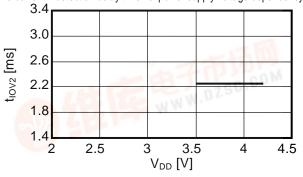
2.6

2.2 1.8

1.4

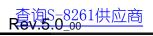
-50

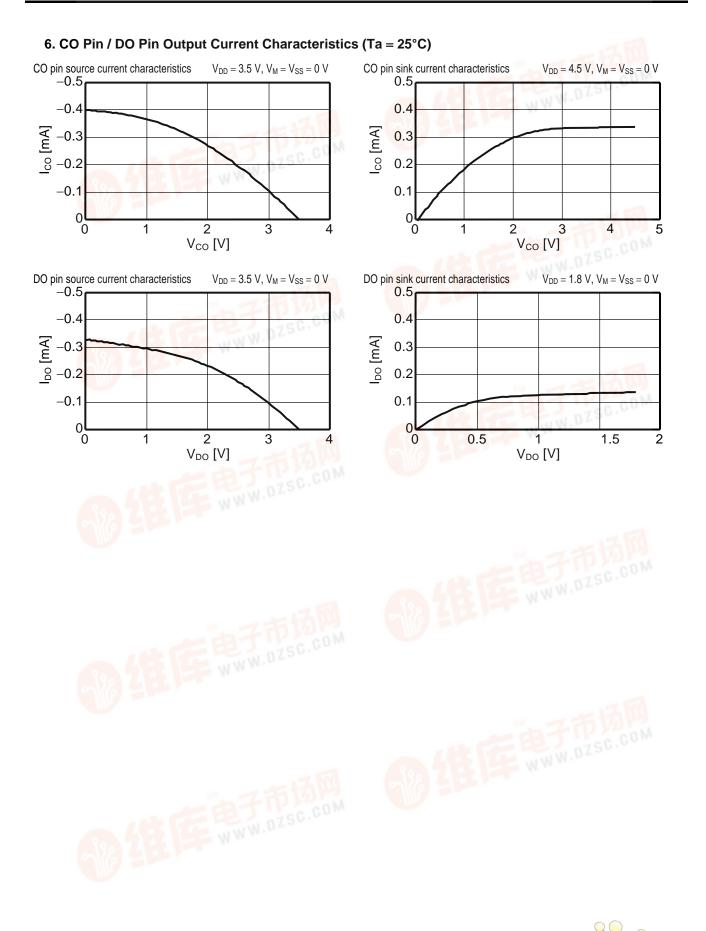
t_{iov2} [ms]







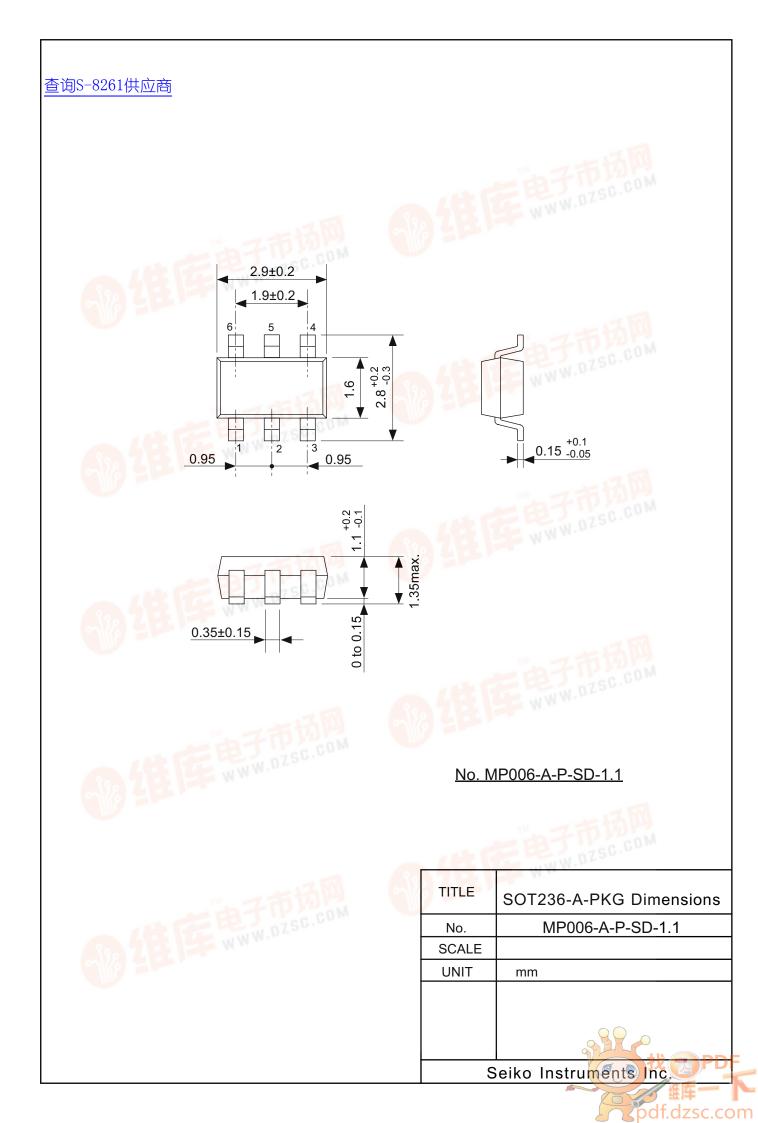




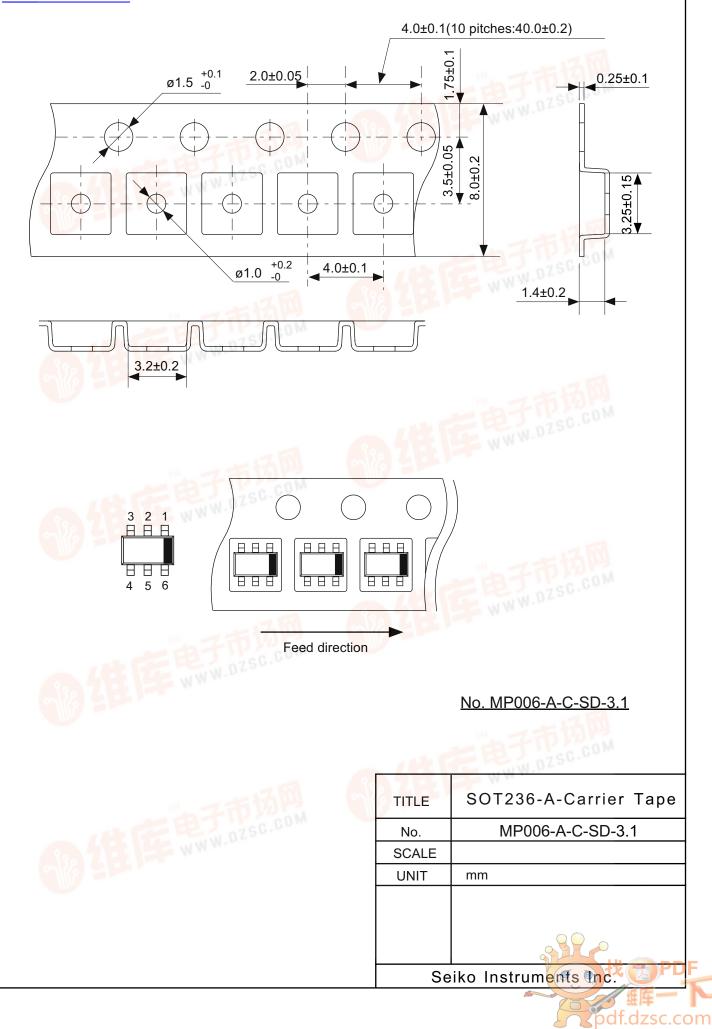
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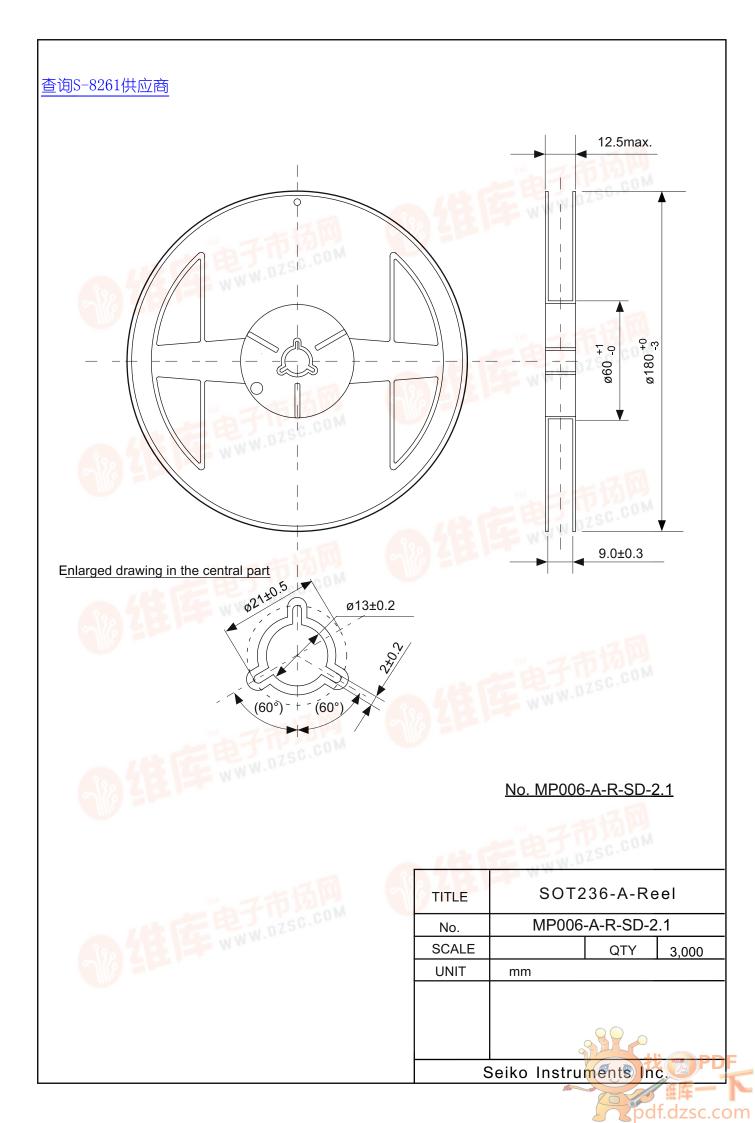
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